

**Amendments to the Specification:**

Please add the following new paragraph on page 7, after line 5:

Fig. 8 is a cross-sectional view showing a printed circuit board according to another embodiment of the present invention.

Please replace the paragraph on page 9, line 22, with the following amended paragraph:

During the plating treatment, it is preferred that the uppermost portion of the plating 5 be formed at a position higher than the upper surface 41 of the solder resist 4 as shown in Fig. 8. This enables the joining of, for example, a solder ball or a solder paste to be performed more easily. Further, when electrically testing the printed circuit board 1, the terminal used during the testing, for example, a probe or an anisotropic conductive rubber body, easily contacts the plating 5. If the uppermost portion of the plating 5 is formed at a position lower than the upper surface 41 of the solder resist 4, the joining and contacting may be difficult.